LEADED

BGA SOLDER PASTE

Sn63/Pb37

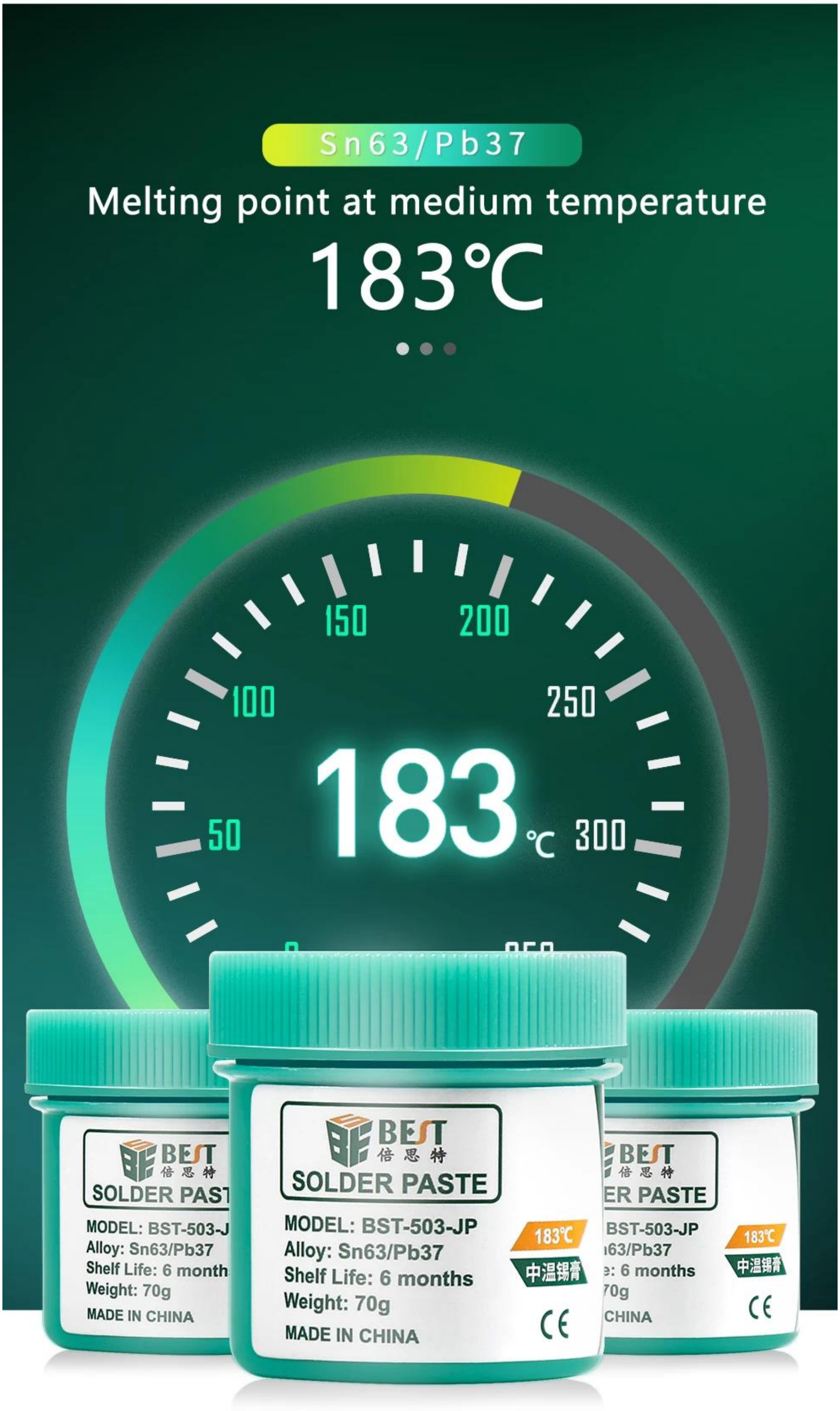
Melting point183℃

Product Usage

TIN PASTE

Type number	BST-503-JP
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183℃
G.W.	70g
size	1.41*1.28 in

PRODUCT INFORMATION




Low residue
BEST
SOLDER PASTE
MODEL: BST-503-JP
Alloy: Sn63/Pb37
Shelf Life: 6 months
Weight: 70g
MADE IN CHINA
CE
Rapid welding
Solder spot bright

Welding requirements for a wide range of products

SMT patch

LED patch

BGA welding

Product List

G.W.:70g